

LM321 Low Power Single Op Amp

Check for Samples: [LM321](#)

FEATURES

- ($V_{CC} = 5V$, $T_A = 25^\circ C$. Typical values unless specified.)
- Gain-Bandwidth Product 1MHz
- Low Supply Current 430 μA
- Low Input Bias Current 45nA
- Wide Supply Voltage Range +3V to +32V
- Stable With High Capacitive Loads
- Single Version of LM324

APPLICATIONS

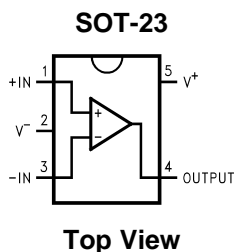
- Chargers
- Power Supplies
- Industrial: Controls, Instruments
- Desktops
- Communications Infrastructure

DESCRIPTION

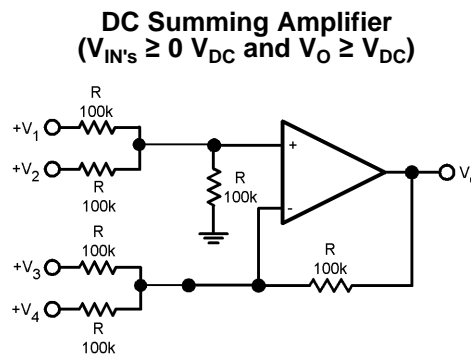
The LM321 brings performance and economy to low power systems. With a high unity gain frequency and a guaranteed 0.4V/ μs slew rate, the quiescent current is only 430 μA /amplifier (5V). The input common mode range includes ground and therefore the device is able to operate in single supply applications as well as in dual supply applications. It is also capable of comfortably driving large capacitive loads.

The LM321 is available in the SOT-23 package. Overall the LM321 is a low power, wide supply range performance op amp that can be designed into a wide range of applications at an economical price without sacrificing valuable board space.

Connection Diagram



Application Circuit



$$\text{Where: } V_O = V_1 + V_2 - V_3 - V_4, (V_1 + V_2) \geq (V_3 + V_4) \text{ to keep } V_O > 0 V_{DC}$$



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings ⁽¹⁾

Differential Input Voltage	±Supply Voltage
Input Current ($V_{IN} < -0.3V$) ⁽²⁾	50mA
Supply Voltage ($V^+ - V^-$)	32V
Input Voltage	-0.3V to +32V
Output Short Circuit to GND, $V^+ \leq 15V$ and $T_A = 25^\circ C$ ⁽³⁾	Continuous
Storage Temperature Range	-65°C to 150°C
Junction Temperature ⁽⁴⁾	150°C
Mounting Temperature	
Lead Temp (Soldering, 10 sec)	260°C
Infrared (10 sec)	215°C
Thermal Resistance to Ambient (θ_{JA})	265°C/W
ESD Tolerance ⁽⁵⁾	300V

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics.
- (2) This input current will only exist when the voltage at any of the input leads is driven negative. It is due to the collector base junction of the input PNP transistors becoming forward biased and thereby acting as input diode clamps. In addition to this diode action, there is also lateral NPN parasitic transistor action on the IC chip. This transistor action can cause the output voltages of the op amps to go to the V^+ voltage level (or to ground for a large overdrive) for the time duration that an input is driven negative. This is not destructive and normal output states will re-establish when the input voltage, which was negative, again returns to a value greater than -0.36V (at 25°C).
- (3) Short circuits from the output V^+ can cause excessive heating and eventual destruction. When considering short circuits to ground the maximum output current is approximately 40mA independent of the magnitude of V^+ . At values of supply voltage in excess of +15V, continuous short circuits can exceed the power dissipation ratings and cause eventual destruction.
- (4) The maximum power dissipation is a function of $T_{J(MAX)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A) / \theta_{JA}$. All numbers apply for packages soldered directly onto a PC board.
- (5) Human Body Model, 1.5kΩ in series with 100pF.

Operating Ratings ⁽¹⁾

Temperature Range	-40°C to 85°C
Supply Voltage	3V to 30V

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics.

Electrical Characteristics

Unless otherwise specified, all limits guaranteed for at $T_A = 25^\circ\text{C}$; $V^+ = 5\text{V}$, $V^- = 0\text{V}$, $V_O = 1.4\text{V}$. **Boldface** limits apply at temperature extremes.

Symbol	Parameter	Conditions	Min (1)	Typ (2)	Max (1)	Units
V_{OS}	Input Offset Voltage	(3)		2	7 9	mV
I_{OS}	Input Offset Current			5	50 150	nA
I_B	Input Bias Current (4)			45	250 500	nA
V_{CM}	Input Common-Mode Voltage Range	$V^+ = 30\text{V}$ (5) For CMRR > = 50dB	0		$V^+ - 1.5$ $V^+ - 2$	V
A_V	Large Signal Voltage Gain	($V^+ = 15\text{V}$, $R_L = 2\text{k}\Omega$ $V_O = 1.4\text{V}$ to 11.4V)	25 15	100		V/mV
PSRR	Power Supply Rejection Ratio	$R_S \leq 10\text{k}\Omega$, $V^+ \leq 5\text{V}$ to 30V	65	100		dB
CMRR	Common Mode Rejection Ratio	$R_S \leq 10\text{k}\Omega$	65	85		dB
V_O	Output Swing	V_{OH}	$V^+ = 30\text{V}$, $R_L = 2\text{k}\Omega$	26		V
			$V^+ = 30\text{V}$, $R_L = 10\text{k}\Omega$	27	28	
		V_{OL}	$V^+ = 5\text{V}$, $R_L = 10\text{k}\Omega$		5	20
I_S	Supply Current, No Load	$V^+ = 5\text{V}$		0.430 0.7	1.15 1.2	mA
		$V^+ = 30\text{V}$		0.660 1.5	2.85 3	
I_{SOURCE}	Output Current Sourcing	$V_{ID} = +1\text{V}$, $V^+ = 15\text{V}$, $V_O = 2\text{V}$	20 10	40 20		mA
I_{SINK}	Output Current Sinking	$V_{ID} = -1\text{V}$ $V^+ = 15\text{V}$, $V_O = 2\text{V}$	10 5	20 8		mA
		$V_{ID} = -1\text{V}$ $V^+ = 15\text{V}$, $V_O = 0.2\text{V}$	12	100		μA
I_O	Output Short Circuit to Ground (6)	$V^+ = 15\text{V}$		40	85	mA
SR	Slew Rate	$V^+ = 15\text{V}$, $R_L = 2\text{k}\Omega$, $V_{IN} = 0.5$ to 3V $C_L = 100\text{pF}$, Unity Gain		0.4		V/ μs
GBW	Gain Bandwidth Product	$V^+ = 30\text{V}$, $f = 100\text{kHz}$, $V_{IN} = 10\text{mV}$, $R_L = 2\text{k}\Omega$, $C_L = 100\text{pF}$		1		MHz
ϕ_m	Phase Margin			60		deg
THD	Total Harmonic Distortion	$f = 1\text{kHz}$, $A_V = 20\text{dB}$ $R_L = 2\text{k}\Omega$, $V_O = 2V_{PP}$, $C_L = 100\text{pF}$, $V^+ = 30\text{V}$		0.015		%
e_n	Equivalent Input Noise Voltage	$f = 1\text{kHz}$, $R_S = 100\Omega$ $V^+ = 30\text{V}$		40		nV/ $\sqrt{\text{Hz}}$

(1) All limits are guaranteed by testing or statistical analysis.

(2) Typical values represent the most likely parametric norm.

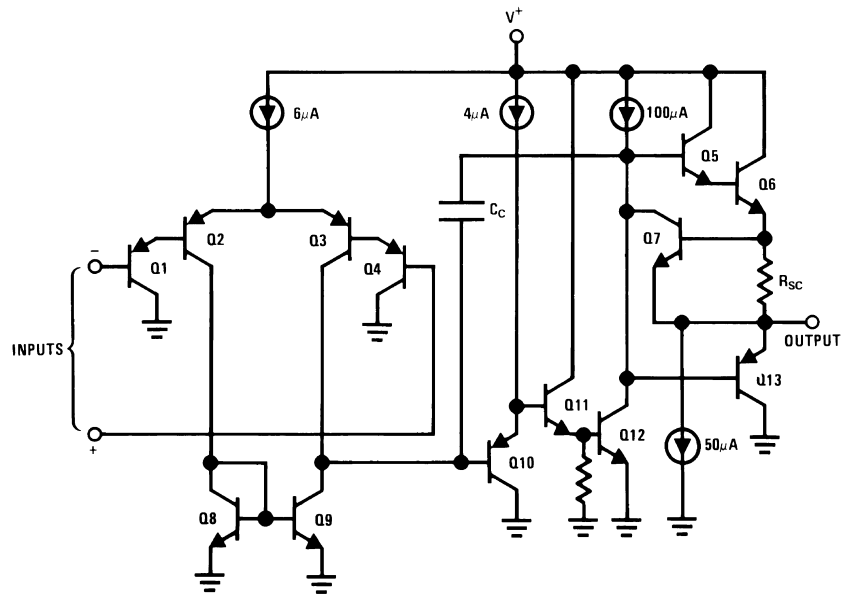
(3) $V_O \cong 1.4\text{V}$, $R_S = 0\Omega$ with V^+ from 5V to 30V ; and over the full input common-mode range (0V to $V^+ - 1.5\text{V}$) at 25°C .

(4) The direction of the input current is out of the IC due to the PNP input stage. This current is essentially constant, independent of the state of the output so no loading change exists on the input lines.

(5) The input common-mode voltage of either input signal voltage should not be allowed to go negative by more than 0.3V (at 25°C). The upper end of the common-mode voltage range is $V^+ - 1.5\text{V}$ at 25°C , but either or both inputs can go to $+32\text{V}$ without damage, independent of the magnitude of V^+ .

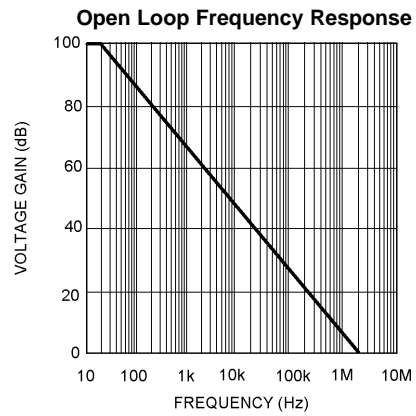
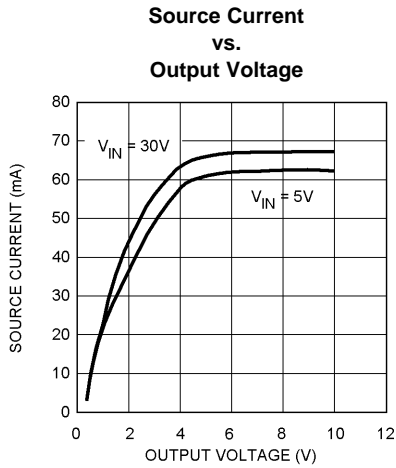
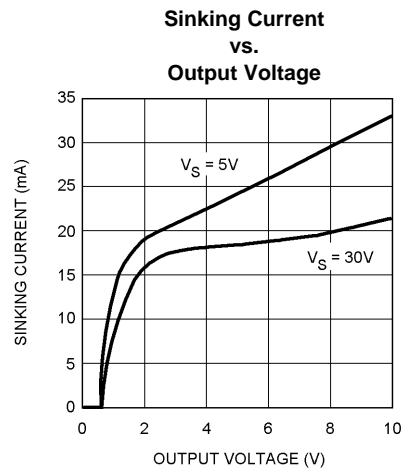
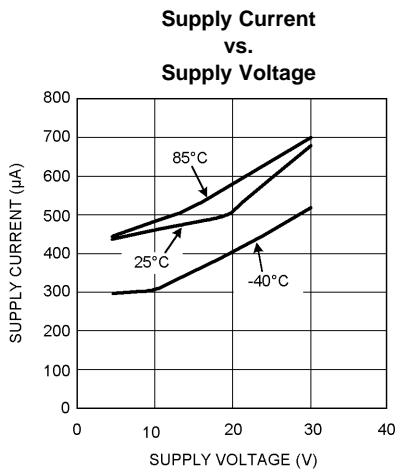
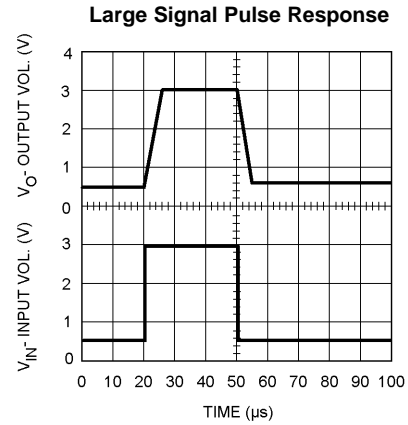
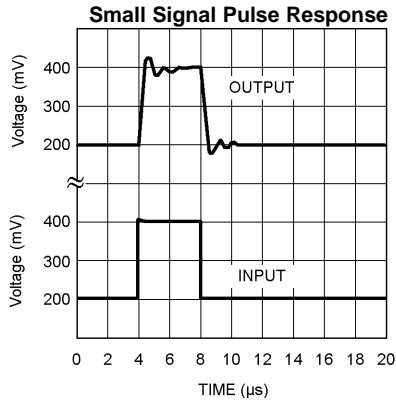
(6) Short circuits from the output V^+ can cause excessive heating and eventual destruction. When considering short circuits to ground the maximum output current is approximately 40mA independent of the magnitude of V^+ . At values of supply voltage in excess of $+15\text{V}$, continuous short circuits can exceed the power dissipation ratings and cause eventual destruction.

Simplified Schematic



Typical Performance Characteristics

Unless otherwise specified, $V_S = +5V$, single supply, $T_A = 25^\circ C$.



APPLICATION HINTS

The LM321 op amp can operate with a single or dual power supply voltage, has true-differential inputs, and remain in the linear mode with an input common-mode voltage of $0 V_{DC}$. This amplifier operates over a wide range of power supply voltages, with little change in performance characteristics. At 25°C amplifier operation is possible down to a minimum supply voltage of 3V.

Large differential input voltages can be easily accommodated and, as input differential voltage protection diodes are not needed, no large input currents result from large differential input voltages. The differential input voltage may be larger than V^+ without damaging the device. Protection should be provided to prevent the input voltages from going negative more than $-0.3 V_{DC}$ (at 25°C). An input clamp diode with a resistor to the IC input terminal can be used.

To reduce the power supply drain, the amplifier has a class A output stage for small signal levels which converts to class B in a large signal mode. This allows the amplifiers to both source and sink large output currents. Therefore both NPN and PNP external current boost transistors can be used to extend the power capability of the basic amplifiers. The output voltage needs to raise approximately 1 diode drop above ground to bias the on-chip vertical PNP transistor for output current sinking applications.

For AC applications, where the load is capacitively coupled to the output of the amplifier, a resistor should be used, from the output of the amplifier to ground to increase the class A bias current and to reduce distortion.

Capacitive loads which are applied directly to the output of the amplifier reduce the loop stability margin. Values of 50pF can be accommodated using the worst-case non-inverting unity gain connection. Large closed loop gains or resistive isolation should be used if large load capacitance must be driven by the amplifier.

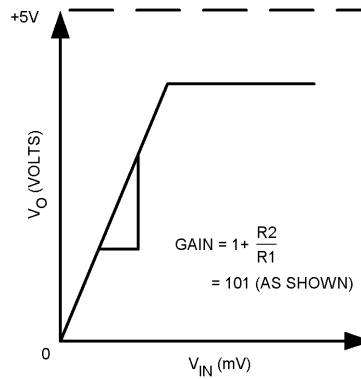
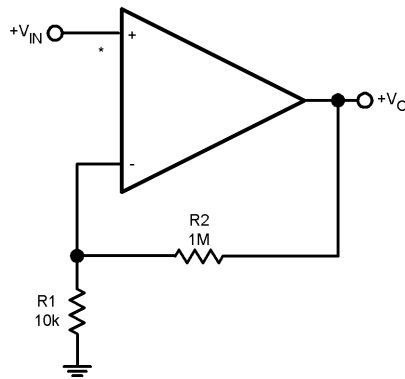
The bias network of the LM321 establishes a supply current which is independent of the magnitude of the power supply voltage over the range of from $3 V_{DC}$ to $30 V_{DC}$.

Output short circuits either to ground or to the positive power supply should be of short time duration. Units can be destroyed, not as a result of the short circuit current causing metal fusing, but rather due to the large increase in IC chip dissipation which will cause eventual failure due to excessive junction temperatures. The larger value of output source current which is available at 25°C provides a larger output current capability at elevated temperatures than a standard IC op amp.

The circuits presented in the section on typical applications emphasize operation on only a single power supply voltage. If complementary power supplies are available, all of the standard op amp circuits can be used. In general, introducing a pseudo-ground (a bias voltage reference of $V^+/2$) will allow operation above and below this value in single power supply systems. Many application circuits are shown which take advantage of the wide input common-mode voltage range which includes ground. In most cases, input biasing is not required and input voltages which range to ground can easily be accommodated.

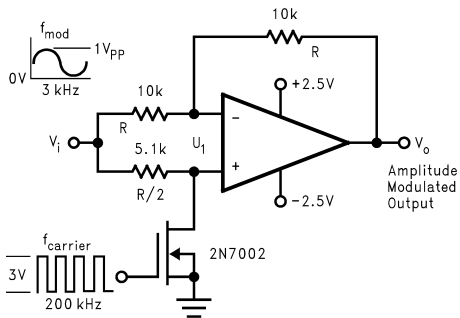
TYPICAL APPLICATIONS

Non-Inverting DC Gain (0V Input = 0V Output)

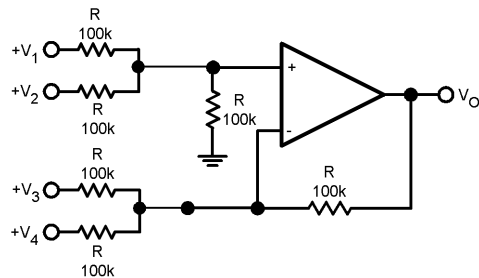


* R NOT NEEDED DUE TO TEMPERATURE INDEPENDENT I_{IN}

Amplitude Modulator Circuit

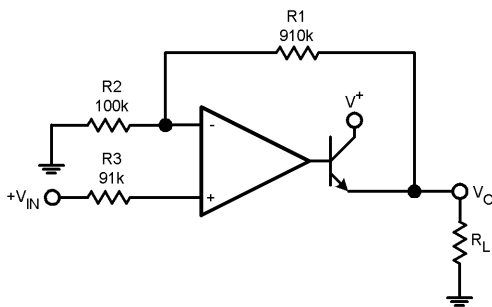


DC Summing Amplifier (V)
($I_{IN's} \geq 0$ V_{DC} and $V_O \geq V_{DC}$)



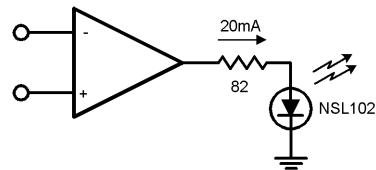
Where: $V_O = V_1 + V_2 - V_3 - V_4$, $(V_1 + V_2) \geq (V_3 + V_4)$ to keep $V_O > 0$ V_{DC}

Power Amplifier

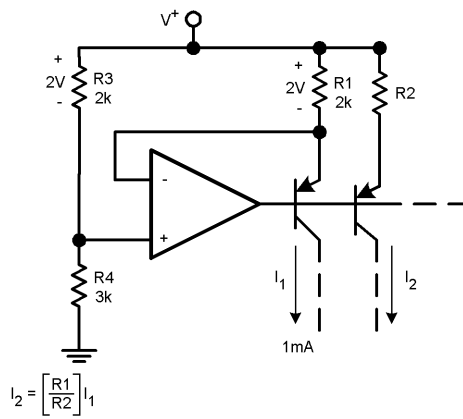


$V_O = 0$ V_{DC} for $V_{IN} = 0$ V_{DC} , $A_V = 10$

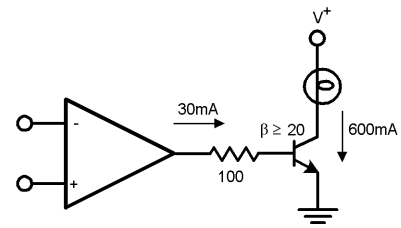
LED Driver







Fixed Current Sources



Lamp Driver



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM321MF	ACTIVE	SOT-23	DBV	5	1000	TBD	CU SNPB	Level-1-260C-UNLIM	-40 to 85	A63A	
LM321MF/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	A63A	
LM321MFX	ACTIVE	SOT-23	DBV	5	3000	TBD	CU SNPB	Level-1-260C-UNLIM	-40 to 85	A63A	
LM321MFX/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	A63A	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM321MF	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LM321MF/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LM321MFX	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LM321MFX/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM321MF	SOT-23	DBV	5	1000	203.0	190.0	41.0
LM321MF/NOPB	SOT-23	DBV	5	1000	203.0	190.0	41.0
LM321MFX	SOT-23	DBV	5	3000	206.0	191.0	90.0
LM321MFX/NOPB	SOT-23	DBV	5	3000	206.0	191.0	90.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com